

## Declaration and Power of Attorney United States Patent Application

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and

UNITED STATES (Form BDWY-1) Patents and Design Patents

Sole & Joint Inventors

Convention & Non-convention

PCT & Non-PCT

This form cannot be amended, althered or changed after it is signed. (For use only for inventors whooint understand the English language.)

is sought on the invention entitled	w) of the subject matter which is claimed	and for which a patent	understand the English language.)
Method and device for Dryin	ig Substrate		, the specification of which
(check one)  is attached hereto.			
uas filed as U.S.Applica	ation No. 09/889, 484	on July 18, 2001	and (if applicable)
was amended on			
☐ was filed as PCT Interna	<del>-</del>	on	
and (if applicable) was	amended under PCT Article 19 on	·	
	ents of the above-identified specification which is material to the examinati		
I heredy claim foreign priority benefits	s under Title 35, United States Code, § 119	(a)-(d) or §365(b) of any foreign and	PCT application(s) for patent or
	ny PCT international application which des		
	dentified below any foreign application i		or PCT international application
having a filing date before that of the	application(s) on which priority is claim	ned:	
Foreign/PCT Application No.	Country	Filing Date	Priority Claimed?(yes/no)
PCT/JP99/04335	PCT	August 10, 1999	Yes
1999/9338	Japan	January 18, 1999	Yes
1999/122696	Japan	April 28,1999	Yes
I hereby claim the benefit under Title 3	35, United States Code, § 120 or § 365(c) of	any United States application and PCT	f international application
designating the United States of America	a listed in this Declaration and, insofar a	as the subject matter of each of the c	claims of this application is not
disclosed in the prior United States app	olication or PCT international application	n in the manner provided by the first	paragraph of Title 35,United States
Code, § 112, I acknowledge the duty to dis	sclose material information as defined in	Title 37, Code of Federal Regulations,	§ 1.56 which occurred between
the filing date of the prior application	and the national or PCT international f	ling date of this application:	
U. S. Application No.	Filing Date		ending/abandoned?)
08/889, 484	July 18, 2001		
	05 th to 1 Court of Call 8 110(a) of call	. Il C provinional application(s) lists	ed below:
	Title 35 United States Code \$119(e)of an	]	Sa scion.
U. S. Provisional Application No.	Filing Date	-	
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I hereby appoint the following attorney:	s to prosecute this application and to tr	20020) Michael A Makuch (32263) Dennis	s C Rodgers
therewith: Joseph A. DeGrandi (17446), Robe	ert G. Weilacher (20531), Richard G. Young (	Mourice II Cobn (30454) and William	I Bundren (31712).
(32936), William F. Rauchholz (34701), G. B	yron Stover (34737), Thomas L. Evans (35805	, Maurice U. Cami (30434), and william	J. Bullut ell (01/12)
Send all correspondence to Beveridge, Det sent to (202)659-1462. Direct all telephone	Grandi, Weilacher & Young, Suite 800, 1850 M one calls to (202)659-2811.	Street, N. W., Washington, D. C. 20036. Fac:	similes may be
true; and further that these statements imprisonment, or both, under Section 1001 application or any patent issued thereo		false statements and the like so maded that such willful false statements	e'are punishable by fine or may jeopardize the validity of the
Full name of sole or first invento	r: Norio MAEDA	Citize	nship: JAPAN
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			(B) (E)
Signature: Norio	MAEDA	Date: 2001, 12	2,5 45 051
☐ Additional inventors and/or prior ap	plications are listed in attached Supplem	ental Sheet(s).	ECHINA BDWY 995

Additional Inventor(s):

أمخا

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Signature:	Koji	SUMI		Da	nte:	2001.	12	5	
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Signature:	masa	00	DNO	Da	ate:	2001.	[2.	5	
	te, country): s: C/O Kar 130	Sakai-shi, ( naoka koujou, 14 Kanaoka-cho L. L.	Osaka 591-8022 J Sakai Seisakush O Sakai-shi, Osa ZUTANI	no of Daikin In	pan			zenship:	JAPAN
Foreign/PCT App			Country		Filing Da	ite		Priority	Claimer?(yes/no)
Additional U.S.		ons:	Bili D.A.		- Cto	tus (patented/	/panding	r/ahandanad	2)
U. S. Applica	tion No.		Filing Date		Sta	cus (patented/	penaing	, avanumeu	
Additional Prov	visional U	J.S. Applicat	ions:						FIVED

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